


Product Specification for Approval

WE ARE PLEASED IN SUBMITTING OUR SAMPLES WITH SPECIFICATION TO YOU FOR APPROVAL.

CUSTOMER	:	
DESCRIPTION	:	POWER INDUCTOR
MNC P/N	:	MCEP125SG1R0M
VERSION	:	A0
CUSTOMER P/N	:	
ISSUED DATE	:	2020/6/9
PHOTO OF PRODUCT	:	
WEIGHT	:	2.75g
MADE IN	:	CHINA

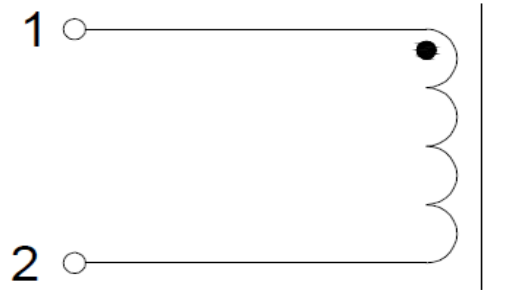
APPROVED BY MNC		
PREPARED BY	CHECKED BY	APPROVED BY
Fanny	Renbo Zhu	Zhiliang Gong

APPROVED BY CUSTOMER
SIGNATURE OR STAMP

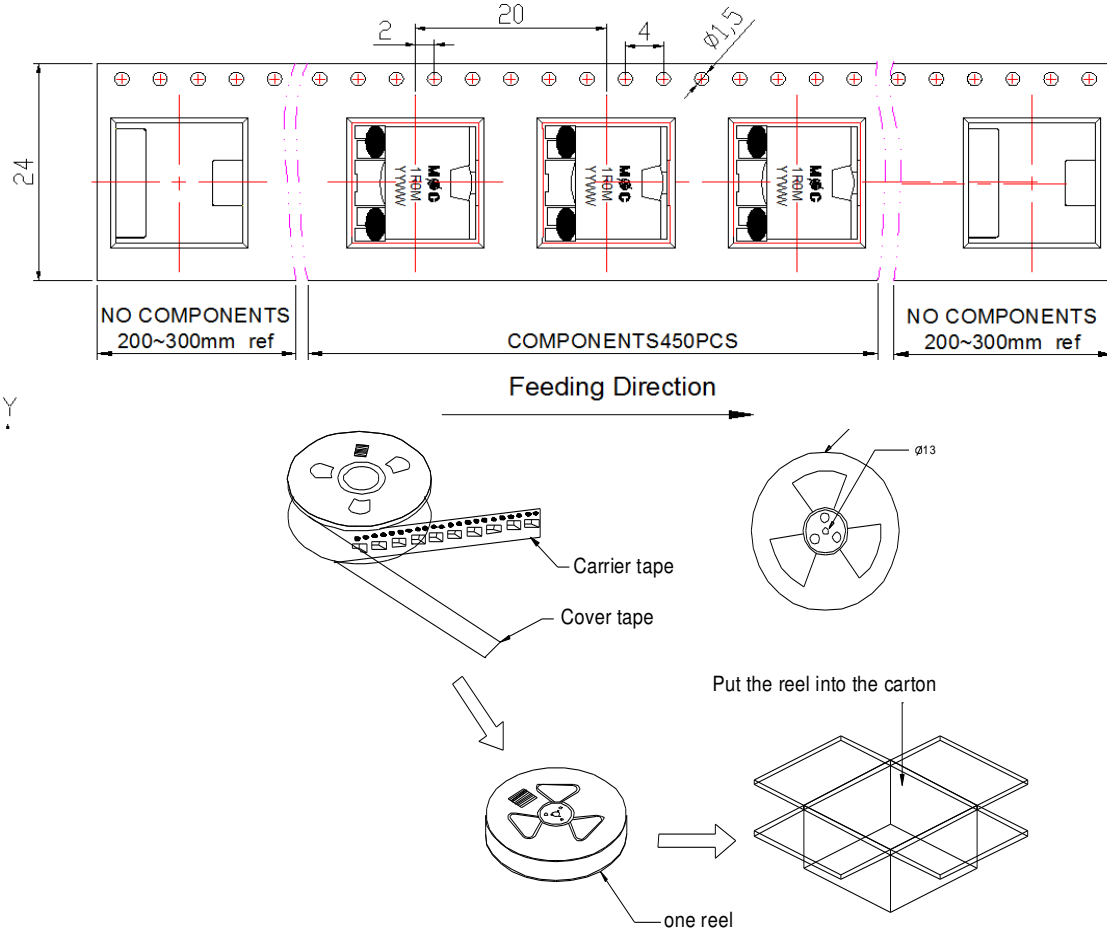
1. PLEASE SEND BACK US A COPY OF THE SPECIFICATION WITH YOUR STAMP OR SIGNATURE ONCE THE SAMPLES APPROVED.
2. IT WILL BE DEEMED THE SAMPLES TO BE APPROVED IF NO FEEDBACK.

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SPECIFICATION
Part No. MCEP125SG1R0M
B. SCHEMATIC :

C. ELECTRICAL SPECIFICATION @25°C

ITEM	SPECIFICATION	TEST CONDITION	TEST EQUIPMENT
L: 1-2	1.0uH \pm 20%	100KHz,0.1V	TH2819XB OR EQU.
DC RESISTANCE: 1-2	2.5m Ω Max	25°C	TH2512B OR EQU.
Q:1-2	20Min	100KHz,0.1V	WK3260B OR EQU.
Isat:1-2	L20A/L0A>70%	100KHz,0.1V	WK3260B+3265B
Irms:1-2	16.5A	100KHz,0.1V	WK3260B+3265B
OPERATING TEMPERATURE RANGE	-40°C to 125°C (Including self temperature rise)		
STORAGE TEMPERATURE RANGE	-40°C to 85°C		

SPECIFICATION
Part No. MCEP125SG1R0M
1. PACKING:
a. PACKAGING AS BELOW (ONLY FOR REFERENCE):

b. Q'TY:

450 pcs/reel
 8 reel/carton
 3600 pcs/carton

c. LABEL:

REMARK:

ABOVE PACKING IS FOR YOUR REFERENCE ONLY, WHICH MIGHT BE CHANGED WITHOUT NOTICE.

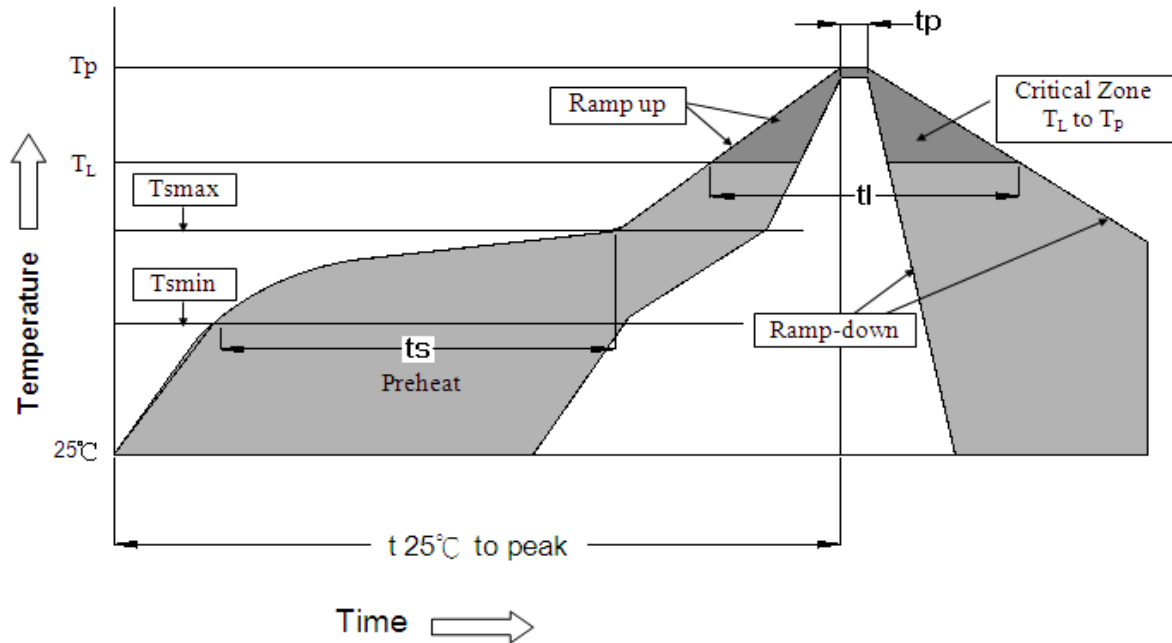
MATERIAL LIST
Part No. MCEP125SG1R0M
BOM

MATERIAL LIST					
NO.	ITEM	MATERIAL	RATING	SUPPLIER OF MATERIAL	UL
1	CORE	Mn-Zn	-----	JIANUO	N/A
			-----	TDG	N/A
2	CASE	PM 9630	150°C	SUMITOMO BAKELITE CO LTD OR EQU.	E41429
3	Flat wire	SFT-EI/AIWJ	220°C	WELL ASCENT ELECTRONIC (GANZHOU) CO LTD	E318511
		@*xEI/AIW	220°C	ZHUHAI SUNTEK WIRE CO.,LTD OR EQU.	E234867
4	EPOXY	6911 G2	150°C	MIANYANG WELLS	N/A
		2089	150°C	DONGGUANG CHENGGE INSULATION MATERIALS CO., LTD	N/A

RECOMMENDED SOLDERING PROFILE

Part No. MCEP125SG1R0M

1. RECOMMENDED REFLOW SOLDERING PROFILE:



$T_L = 217^\circ C$

$T_p = 245^\circ C$

$t_s = 60-120s$ $T_s \text{ max} = 200^\circ C$ $T_s \text{ min} = 150^\circ C$

$t_l = 60-150s$ $t_p = 20-40s$ $T_{25^\circ C \text{ to peak}} = 8\text{min max}$

Ramp up rate = $3^\circ C/s$ max

Ramp down rate = $6^\circ C/s$ max

*RoHS Compliant

*Solder Paste SAC 305 Sn 96.5/Ag 3.0/Cu 0.5

*Silkscreen thickness: 0.15mm Min

2. MOISTURE SENSITIVE LEVEL:

2.1. Level: 1

2.2. Shelf Life: Unlimited

2.3. Storage Condition: $\leq 30^\circ C/85\% RH$